

MATERIAL DECLARATION SHEET



Package Type	Axial			
Product Line	PTVS15-058C-TH			
Compliance Date	August 1 st 2012			
RoHS Compliant	Yes	MSL	Not Applicable	

No.	Construction Element (subpart)	Homogenous Material	Material Weight (g)	Homogenous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart Mass % of total unit wt.	Material Weight (g)
1	Encapsulation	Epoxy Resin	0.836600	Bisphenol Epoxy Resin	1675-54-3	40.00	7.49	18.71	0.335
				Epoxy Resin	25085-99-8	20.00	3.74		0.167
				Crystalline Silica	14464-46-1	23.00	4.30		0.192
				Brominated Epoxy Resin	40039-93-8	12.00	2.25		0.100
				Iron Oxide	51274-00-1	2.00	0.37		0.017
				Titanium Oxide	13463-67-7	3.00	0.56		0.025
2	Electrodes	Copper	2.644175	Copper	7440-50-8	99.10	58.62	59.15	2.620
				Silver	7440-22-4	0.40	0.24		0.011
				Other	-	0.50	0.30		0.013
3	Terminations	Copper	0.503299	Copper	7440-50-8	99.50	11.20	11.26	0.501
				Other	-	0.50	0.06		0.003
4	Termination Finish	Silver	0.001821	Silver	7440-22-4	100.00	0.04	0.04	0.002
5	Chip	Silicon Die	0.212811	Silicon	7440-21-3	85.34	4.06	4.76	0.182
				Aluminium	7429-90-5	5.13	0.24		0.011
				Nickel	7440-02-0	9.09	0.43		0.019
				Gold	7440-57-5	0.44	0.02		0.001
6	Die Attach	Solder	0.160574	Lead	7439-92-1	92.50	3.32	3.59	0.149
				Tin	7440-31-5	5.00	0.18		0.008
				Silver	7440-22-4	2.50	0.09		0.004
7	Die Coating	Silicone	0.111140	Polysiloxane	trade secret	22.11	0.55	2.49	0.025
				Chromium Sesquioxide	1308-38-9	5.67	0.14		0.006
				Fumed Silica	112945-52-5	11.11	0.28		0.012
				Filler	trade secret	61.11	1.52		0.068
		Total Weight	4.470420						